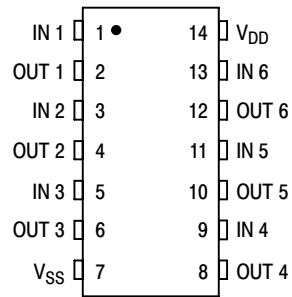
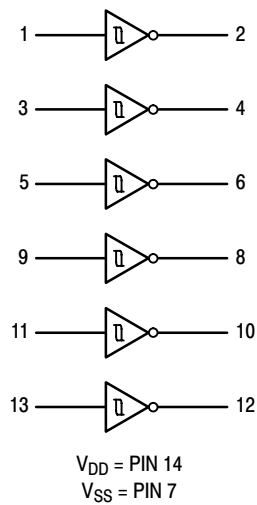


# MC14584B

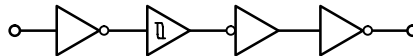
## PIN ASSIGNMENT



## LOGIC DIAGRAM



## EQUIVALENT CIRCUIT SCHEMATIC (1/6 OF CIRCUIT SHOWN)



## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC14584BCP	PDIP-14	25 Units / Rail
MC14584BCPG	PDIP-14 (Pb-Free)	
MC14584BD	SOIC-14	55 Units / Rail
MC14584BDG	SOIC-14 (Pb-Free)	
MC14584BDR2	SOIC-14	2500 / Tape & Reel
MC14584BDR2G	SOIC-14 (Pb-Free)	
MC14584BDTR2	TSSOP-14*	
MC14584BDTR2G	TSSOP-14*	
MC14584BF	SOEIAJ-14	50 Units / Rail
MC14584BFG	SOEIAJ-14 (Pb-Free)	
MC14584BFEL	SOEIAJ-14	2000 / Tape & Reel
MC14584BFELG	SOEIAJ-14 (Pb-Free)	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

# MC14584B

## ELECTRICAL CHARACTERISTICS (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>DD</sub> Vdc	- 55° C		25° C			125° C		Unit
			Min	Max	Min	Typ <sup>(2)</sup>	Max	Min	Max	
Output Voltage V <sub>in</sub> = V <sub>DD</sub>  V <sub>in</sub> = 0	“0” Level V <sub>OL</sub>	5.0	–	0.05	–	0	0.05	–	0.05	Vdc
		10	–	0.05	–	0	0.05	–	0.05	
		15	–	0.05	–	0	0.05	–	0.05	
	“1” Level V <sub>OH</sub>	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc
		10	9.95	–	9.95	10	–	9.95	–	
		15	14.95	–	14.95	15	–	14.95	–	
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)  (V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	Source I <sub>OH</sub>	5.0	– 3.0	–	– 2.4	– 4.2	–	– 1.7	–	mAdc
		5.0	– 0.64	–	– 0.51	– 0.88	–	– 0.36	–	
		10	– 1.6	–	– 1.3	– 2.25	–	– 0.9	–	
		15	– 4.2	–	– 3.4	– 8.8	–	– 2.4	–	
	Sink I <sub>OL</sub>	5.0	0.64	–	0.51	0.88	–	0.36	–	mAdc
		10	1.6	–	1.3	2.25	–	0.9	–	
		15	4.2	–	3.4	8.8	–	2.4	–	
Input Current	I <sub>in</sub>	15	–	±0.1	–	±0.00001	±0.1	–	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	–	–	–	–	5.0	7.5	–	–	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0	–	0.25	–	0.0005	0.25	–	7.5	μAdc
		10	–	0.5	–	0.0010	0.5	–	15	
		15	–	1.0	–	0.0015	1.0	–	30	
Total Supply Current <sup>(3) (4)</sup> (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	I <sub>T</sub>	5.0 10 15	I <sub>T</sub> = (1.8 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (3.6 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (5.4 μA/kHz) f + I <sub>DD</sub>							μAdc
Hysteresis Voltage	V <sub>H</sub> <sup>(5)</sup>	5.0	0.27	1.0	0.25	0.6	1.0	0.21	1.0	Vdc
		10	0.36	1.3	0.3	0.7	1.2	0.25	1.2	
		15	0.77	1.7	0.6	1.1	1.5	0.50	1.4	
Threshold Voltage Positive-Going  Negative-Going	V <sub>T+</sub>	5.0	1.9	3.5	1.8	2.7	3.4	1.7	3.4	Vdc
		10	3.4	7.0	3.3	5.3	6.9	3.2	6.9	
		15	5.2	10.6	5.2	8.0	10.5	5.2	10.5	
	V <sub>T–</sub>	5.0	1.6	3.3	1.6	2.1	3.2	1.5	3.2	Vdc
		10	3.0	6.7	3.0	4.6	6.7	3.0	6.7	
		15	4.5	9.7	4.6	6.9	9.8	4.7	9.9	

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

3. The formulas given are for the typical characteristics only at 25° C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) V f k$$

where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> – V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.001.

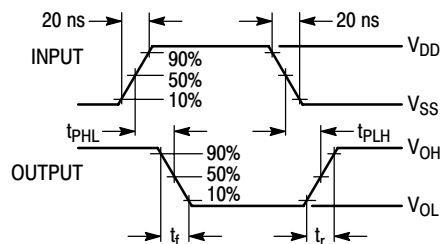
5. V<sub>H</sub> = V<sub>T+</sub> – V<sub>T–</sub> (But maximum variation of V<sub>H</sub> is specified as less than V<sub>T+ max</sub> – V<sub>T– min</sub>).

## SWITCHING CHARACTERISTICS (C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25° C)

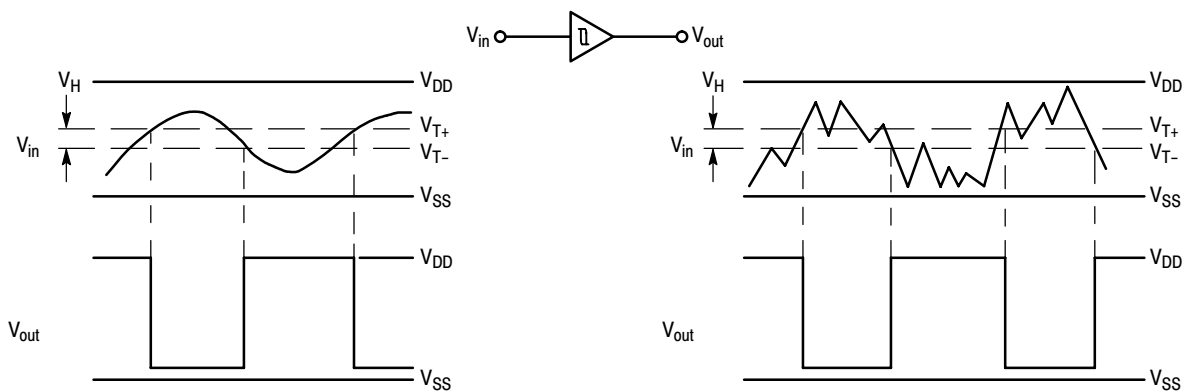
Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Typ <sup>(6)</sup>	Max	Unit
Output Rise Time	t <sub>TLH</sub>	5.0	–	100	200	ns
		10	–	50	100	
		15	–	40	80	
Output Fall Time	t <sub>THL</sub>	5.0	–	100	200	ns
		10	–	50	100	
		15	–	40	80	
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0	–	125	250	ns
		10	–	50	100	
		15	–	40	80	

6. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

## MC14584B

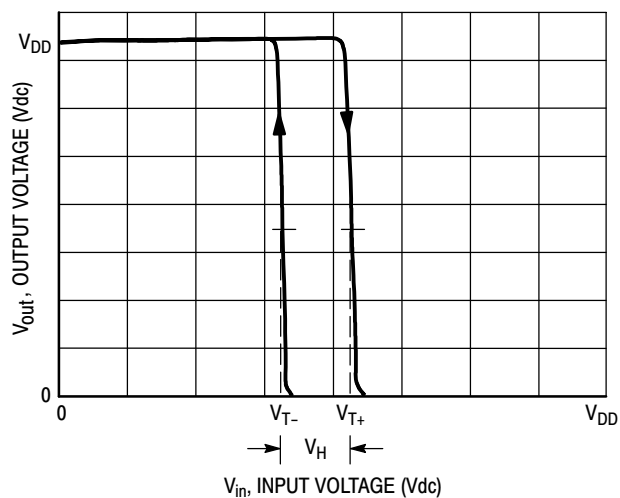


### Figure 1. Switching Time Test Circuit and Waveforms



**(b) A Schmitt trigger offers maximum noise immunity in gate applications.**

### Figure 2. Typical Schmitt Trigger Applications

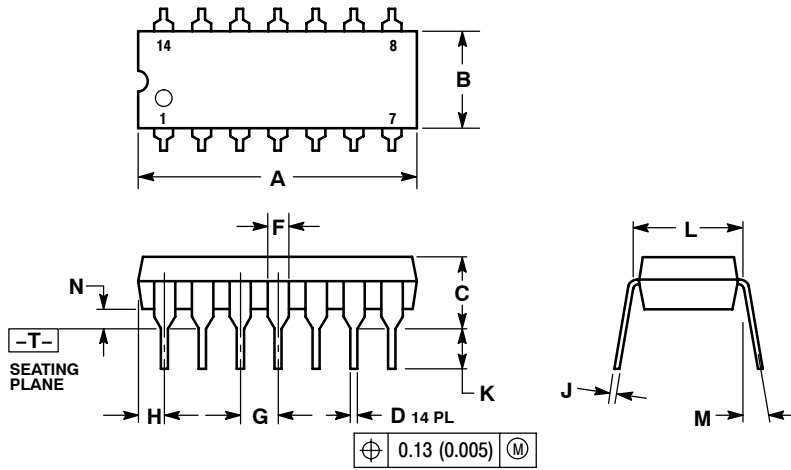


### Figure 3. Typical Transfer Characteristics

# MC14584B

## PACKAGE DIMENSIONS

**PDIP-14**  
CASE 646-06  
ISSUE P



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

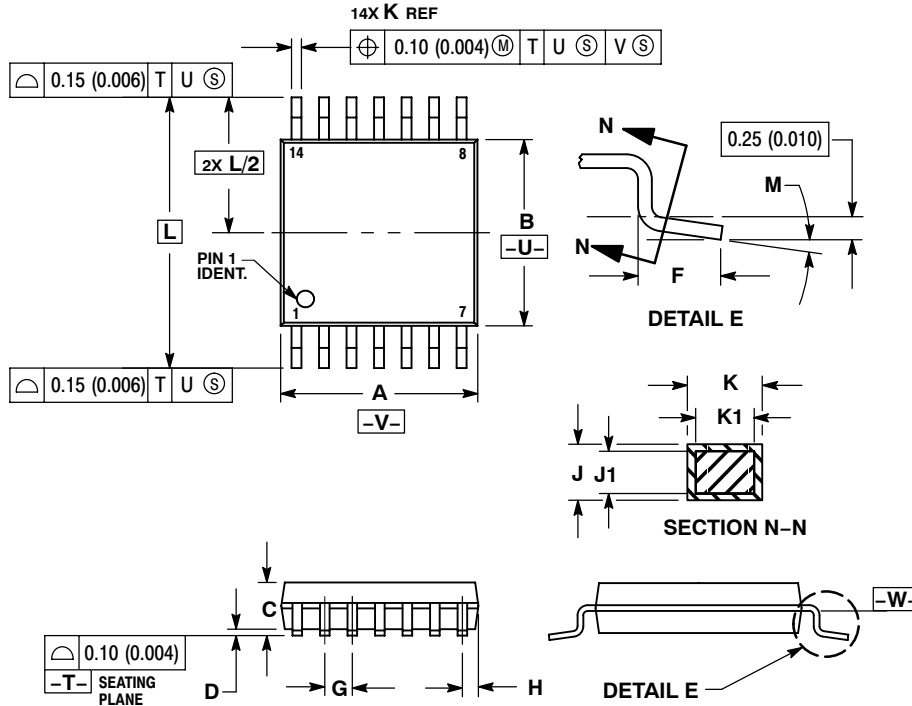
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10 °	---	10 °
N	0.015	0.039	0.38	1.01



# MC14584B

## PACKAGE DIMENSIONS

TSSOP-14  
CASE 948G-01  
ISSUE B

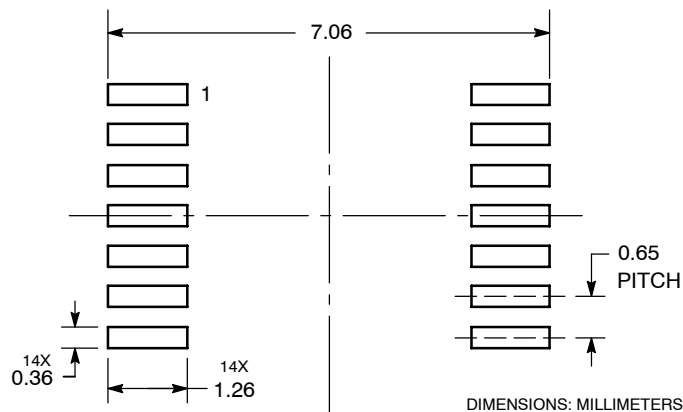


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

### SOLDERING FOOTPRINT\*

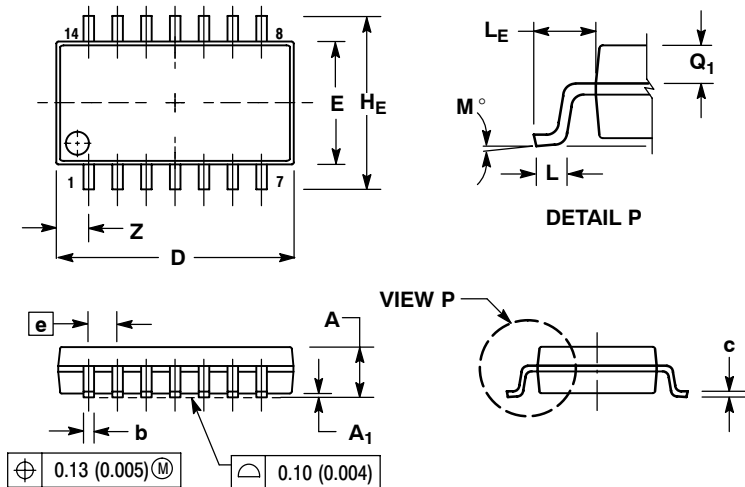


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC14584B

## PACKAGE DIMENSIONS

SOEIAJ-14  
CASE 965-01  
ISSUE A



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H <sub>E</sub>	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
L <sub>E</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

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